

RD3P08BBD

Nch 100V 80A Power MOSFET

V <sub>DSS</sub>	100V
R <sub>DS(on)</sub> (Max.)	11.6mΩ
I <sub>D</sub>	±80A
P <sub>D</sub>	119W

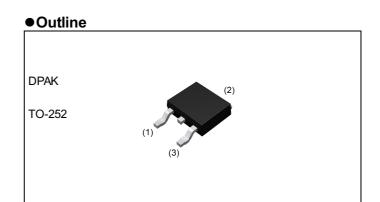
## Features

- 1) Low on resistance
- 2) High power small mold package
- 3) Pb-free lead plating ; RoHS compliant
- 4) 100% Rg and UIS tested
- 5) Halogen free

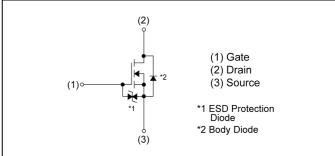
Application

Switching

Power tool



#### Inner circuit



## Packaging specifications

Туре	Packing	Embossed Tape
	Reel size (mm)	330
	Tape width (mm)	16
	Basic ordering unit (pcs)	2500
	Taping code	TL
	Marking	RD3P08BBD

## • Absolute maximum ratings (T<sub>a</sub> = 25°C ,unless otherwise specified)

Parameter	Symbol	Value	Unit		
Drain - Source voltage		V <sub>DSS</sub>	100	V	
Continuous drain current	V <sub>GS</sub> = 10V	۱ <sub>D</sub> *1	±80	А	
Pulsed drain current	۱ <sub>DP</sub> *2	±160	А		
Gate - Source voltage		V <sub>GSS</sub>	±20	V	
Avalanche current, single pulse	I <sub>AS</sub> *3	27	А		
Avalanche energy, single pulse	E <sub>AS</sub> *3	29	mJ		
Power dissipation		P <sub>D</sub> <sup>*1</sup>	119	W	
Junction temperature	Tj	150	°C		
Operating junction and storage tempe	T <sub>stg</sub>	-55 to +150	°C		

## Thermal resistance

Parameter	Symbol	Values			Linit
Farameter	Symbol	Min.	Тур.	Max.	Unit
Thermal resistance, junction - case	R <sub>thJC</sub> *1	-	-	1.05	°C/W

## •Electrical characteristics (T<sub>a</sub> = 25°C)

Deremeter	Currence of	Conditions		Values		Unit	
Parameter	Symbol Conditions		Min.	Тур.	Max.	Unit	
Drain - Source breakdown voltage	V <sub>(BR)DSS</sub>	V <sub>GS</sub> = 0V, I <sub>D</sub> = 1mA	100	-	-	V	
Breakdown voltage temperature coefficient	$\frac{\Delta V_{(BR)DSS}}{\Delta T_j}$	$\frac{\Delta V_{(BR)DSS}}{\Delta T_{j}} I_{D} = 1 mA$ referenced to 25°C		98.33	-	mV/°C	
Zero gate voltage drain current	I <sub>DSS</sub>	V <sub>DS</sub> = 100V, V <sub>GS</sub> = 0V	-	-	10	μA	
Gate - Source leakage current	I <sub>GSS</sub>	$V_{GS}$ = ±20V, $V_{DS}$ = 0V	I	-	±10	μA	
Gate threshold voltage	$V_{GS(th)}$	V <sub>DS</sub> = 10V, I <sub>D</sub> = 1mA	2.0	-	4.0	V	
Gate threshold voltage temperature coefficient	$\frac{\Delta V_{GS(th)}}{\Delta T_j}$	I <sub>D</sub> = 1mA referenced to 25°C	-	-8.28	-	mV/°C	
Static drain - source	D *4	V <sub>GS</sub> = 10V, I <sub>D</sub> = 80A	-	8.6	11.6		
on - state resistance	${R}_{DS(on)}^{*4}$	V <sub>GS</sub> = 6V, I <sub>D</sub> = 40A	-	9.7	16.0	mΩ	
Gate resistance	R <sub>G</sub>	f = 1MHz, open drain	-	4.4	-	Ω	
Forward Transfer Admittance	Y <sub>fs</sub>  *4	V <sub>DS</sub> = 5V, I <sub>D</sub> = 40A	22	-	-	S	

\*1 T<sub>c</sub>=25°C, Limited only by maximum temperature allowed.

\*2 Pw $\leq$ 10µs , Duty cycle $\leq$ 1%

\*3 L  $\simeq$  0.05mH, V\_{DD} = 50V, R\_G = 25 $\Omega$ , Starting T\_j = 25°C Fig.3-1,3-2

\*4 Pulsed



# •Electrical characteristics (T<sub>a</sub> = 25°C)

Deremeter	Cumphol	Conditions	Values			Unit
Parameter	Symbol	Symbol Conditions		Тур.	Max.	Unit
Input capacitance	C <sub>iss</sub>	V <sub>GS</sub> = 0V	-	1940	-	
Output capacitance	C <sub>oss</sub>	V <sub>DS</sub> = 50V	-	270	-	pF
Reverse transfer capacitance	C <sub>rss</sub>	f = 1MHz	-	60	-	
Turn - on delay time	t <sub>d(on)</sub> *4	$V_{DD} \simeq 50V, V_{GS}$ = 10V	-	24	-	
Rise time	t <sub>r</sub> *4	I <sub>D</sub> = 40A	-	8	-	
Turn - off delay time	t <sub>d(off)</sub> *4	R <sub>L</sub> ≃ 1.25Ω	-	66	-	ns
Fall time	t <sub>f</sub> *4	R <sub>G</sub> = 10Ω	-	5	-	

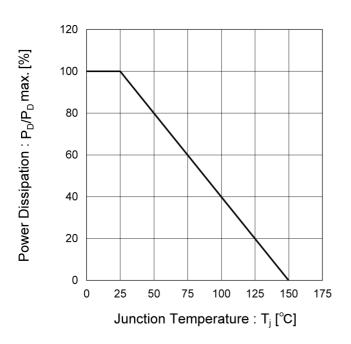
# • Gate charge characteristics ( $T_a = 25^{\circ}C$ )

Deremeter	Sumbol	Conditions		Values			Unit
Parameter	Symbol			Min.	Тур.	Max.	Unit
Tatal gata abarga	O *4		V <sub>GS</sub> = 10V	-	37.0	-	
Total gate charge	Q <sub>g</sub> *4	V <sub>DD</sub> ≃ 50V		-	22.5	-	
Gate - Source charge	Q <sub>gs</sub> *4	I <sub>D</sub> = 40A	V <sub>GS</sub> = 6V	-	10.9	-	nC
Gate - Drain charge	Q <sub>gd</sub> *4			-	8.1	-	

## •Body diode electrical characteristics (Source-Drain) (T<sub>a</sub> = 25°C)

Deremeter	Symbol Conditions		Values			Unit
Parameter	Symbol	Conditions	Min.	Тур.	Max.	Unit
Continuous forward current	۱ <sub>s</sub>	T <sub>a</sub> = 25°C	-	-	80	А
Pulse forward current	$I_{SP}^{*2}$	$T_{a} = 25 C$	-	-	160	А
Forward voltage	$V_{SD}^{*4}$	V <sub>GS</sub> = 0V, I <sub>S</sub> = 80A	-	-	1.2	V
Reverse recovery time	t <sub>rr</sub> *4	I <sub>S</sub> = 50A, V <sub>GS</sub> =0V	-	54	-	ns
Reverse recovery charge	Q <sub>rr</sub> *4	di/dt = 100A/µs	-	118	-	nC





## Fig.1 Power Dissipation Derating Curve

Fig.2 Maximum Safe Operating Area

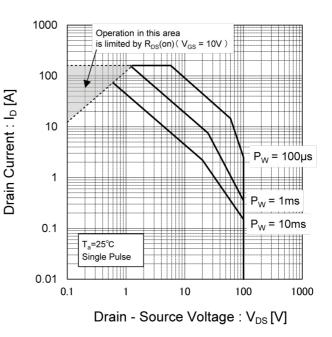
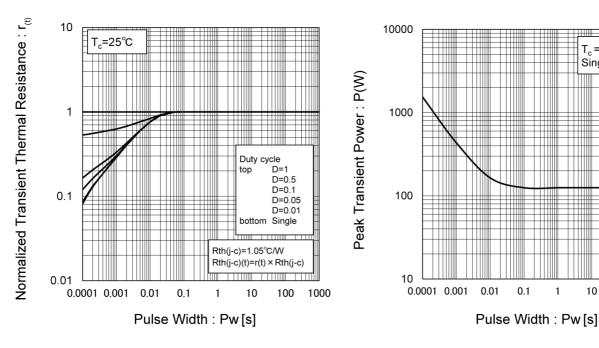


Fig.3 Normalized Transient Thermal Resistance vs. Pulse Width

Fig.4 Single Pulse Maximum Power dissipation



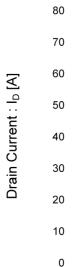


10

100

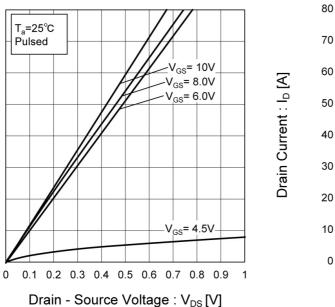
1000

T<sub>c</sub> = 25°C Single Pulse



#### Fig.5 Typical Output Characteristics(I)

Fig.6 Typical Output Characteristics(II)



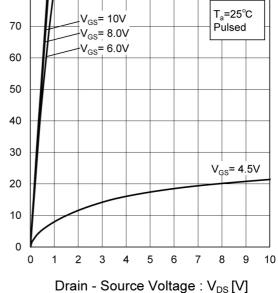
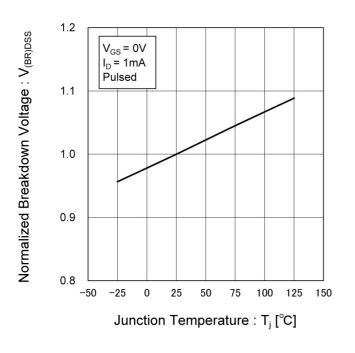
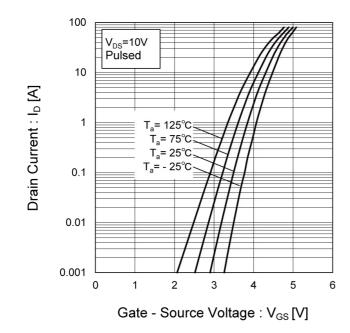


Fig.7 Breakdown Voltage vs. Junction Temperature

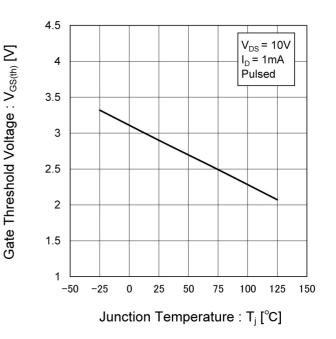




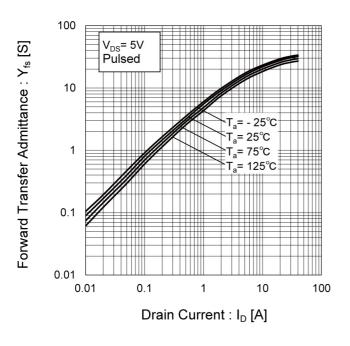


# Fig.8 Typical Transfer Characteristics

Fig.9 Gate Threshold Voltage vs. Junction Temperature



## Fig.10 Forward Transfer Admittance vs. Drain Current





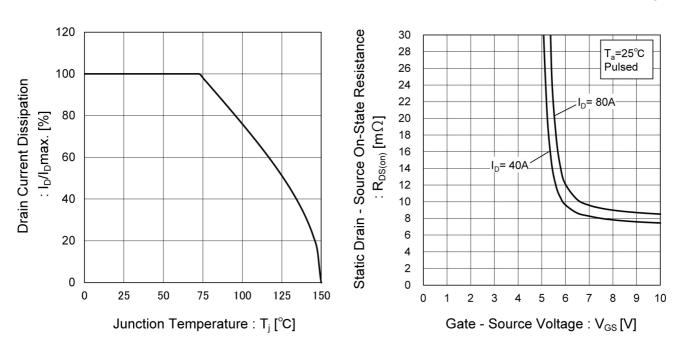
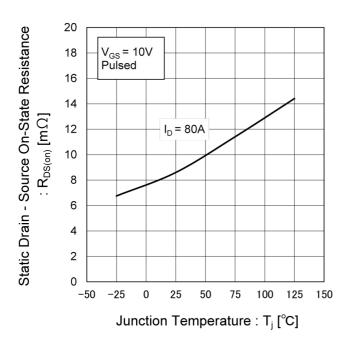


Fig.11 Drain Current Derating Curve

## Fig.12 Static Drain - Source On - State Resistance vs. Gate Source Voltage

Fig.13 Static Drain - Source On - State Resistance vs. Junction Temperature







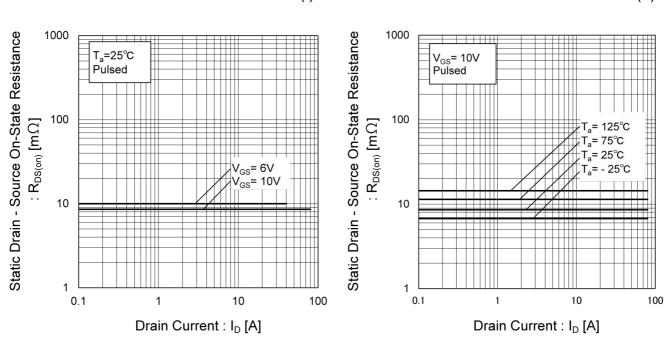
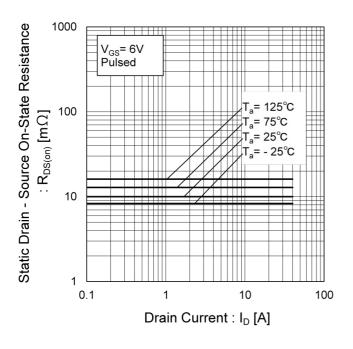
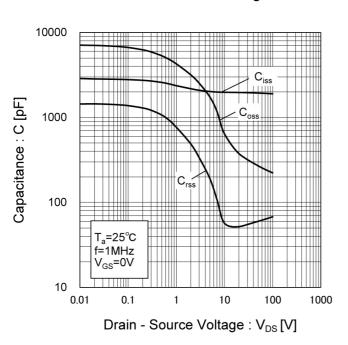


Fig.14 Static Drain - Source On - State Resistance vs. Drain Current (I) Fig.15 Static Drain - Source On - State Resistance vs. Drain Current (II)

Fig.16 Static Drain - Source On - State Resistance vs. Drain Current (III)







#### Fig.17 Typical Capacitance vs. Drain - Source Voltage

Fig.18 Switching Characteristics

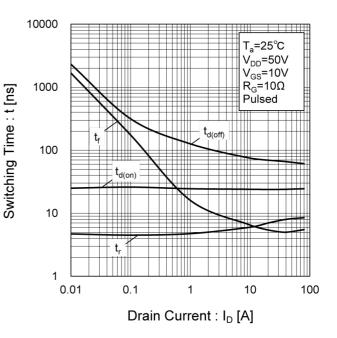


Fig.19 Dynamic Input Characteristics

Gate - Source Voltage : V<sub>GS</sub> [V]

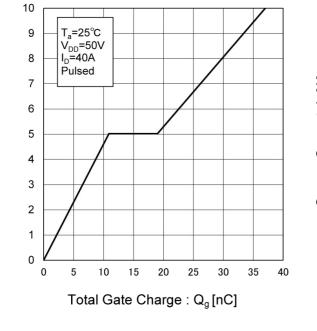
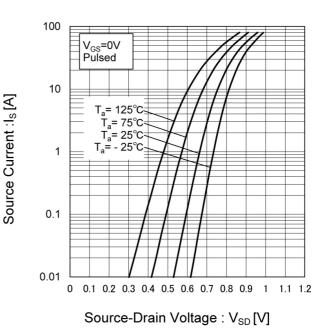


Fig.20 Source Current vs. Source Drain Voltage





## Measurement circuits

Fig.1-1 Switching Time Measurement Circuit

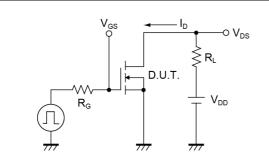


Fig.2-1 Gate Charge Measurement Circuit

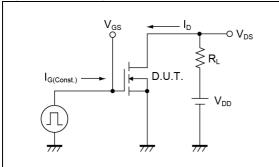


Fig.3-1 Avalanche Measurement Circuit

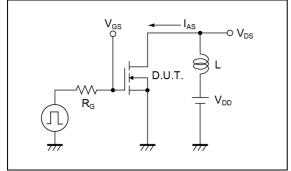


Fig.1-2 Switching Waveforms

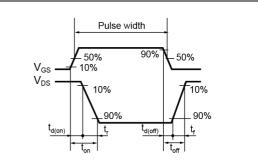
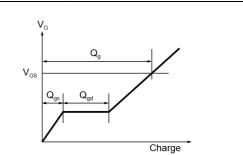
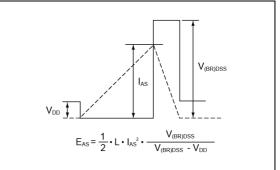


Fig.2-2 Gate Charge Waveform

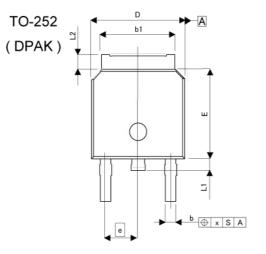


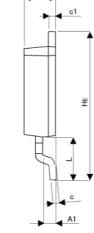
#### Fig.3-2 Avalanche Waveform

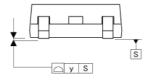


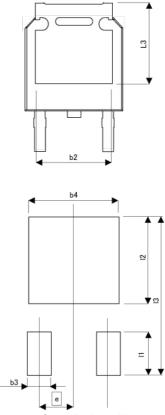


#### Dimensions









Pattern of terminal position areas [Not a recommended pattern of soldering pads]

DIM	MILIME	ETERS	INC	HES
DIM	MIN	MAX	MIN	MAX
A	2.10	2.30	0.083	0.091
A1	0.70	1.10	0.028	0.043
b	0.65	0.85	0.026	0.033
b1	5.10	5.40	0.201	0.213
b2	5.	10	0.2	01
С	0.40	0.60	0.016	0.024
c1	0.40	0.60	0.016	0.024
D	6.40	6.80	0.252	0.268
е	2.	30	0.0	91
E	6.00	6.40	0.236	0.252
HE	9.50	10.50	0.374	0.413
L	2.90		0.1	14
L1	0.70	0.90	0.028	0.035
L2	0.70	1.30	0.028	0.051
L3	5.	30	0.2	09
х	-	0.10	( <b>-</b> )	0.004
у	-	0.10	-	0.004

DIM MILIME		ETERS	INCHES	
Divi	MIN	MAX	MIN	MAX
b3	-	1.10	_	0.043
b4	-	5.40	8 <del>-</del> 8	0.213
l1	-	2.90	-	0.114
12	-	5.50	-	0.217
13	-	10.50	-	0.413

Dimension in mm/inches



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CLASSⅢ	CLASSⅢ	CLASS II b	CLASSII
CLASSⅣ	CLASSII	CLASSⅢ	CLASSI

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  - [f] Sealing or coating our Products with resin or other coating materials
  - [g] Use of our Products without cleaning residue of flux (even if you use no-clean type fluxes, cleaning residue of flux is recommended); or Washing our Products by using water or water-soluble cleaning agents for cleaning residue after soldering
  - [h] Use of the Products in places subject to dew condensation
- 4. The Products are not subject to radiation-proof design.
- 5. Please verify and confirm characteristics of the final or mounted products in using the Products.
- 6. In particular, if a transient load (a large amount of load applied in a short period of time, such as pulse. is applied, confirmation of performance characteristics after on-board mounting is strongly recommended. Avoid applying power exceeding normal rated power; exceeding the power rating under steady-state loading condition may negatively affect product performance and reliability.
- 7. De-rate Power Dissipation depending on ambient temperature. When used in sealed area, confirm that it is the use in the range that does not exceed the maximum junction temperature.
- 8. Confirm that operation temperature is within the specified range described in the product specification.
- 9. ROHM shall not be in any way responsible or liable for failure induced under deviant condition from what is defined in this document.

#### Precaution for Mounting / Circuit board design

- 1. When a highly active halogenous (chlorine, bromine, etc.) flux is used, the residue of flux may negatively affect product performance and reliability.
- 2. In principle, the reflow soldering method must be used on a surface-mount products, the flow soldering method must be used on a through hole mount products. If the flow soldering method is preferred on a surface-mount products, please consult with the ROHM representative in advance.

For details, please refer to ROHM Mounting specification

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- 1. If change is made to the constant of an external circuit, please allow a sufficient margin considering variations of the characteristics of the Products and external components, including transient characteristics, as well as static characteristics.
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This Product is electrostatic sensitive product, which may be damaged due to electrostatic discharge. Please take proper caution in your manufacturing process and storage so that voltage exceeding the Products maximum rating will not be applied to Products. Please take special care under dry condition (e.g. Grounding of human body / equipment / solder iron, isolation from charged objects, setting of lonizer, friction prevention and temperature / humidity control).

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  - [b] the temperature or humidity exceeds those recommended by ROHM
  - [c] the Products are exposed to direct sunshine or condensation
  - [d] the Products are exposed to high Electrostatic
- 2. Even under ROHM recommended storage condition, solderability of products out of recommended storage time period may be degraded. It is strongly recommended to confirm solderability before using Products of which storage time is exceeding the recommended storage time period.
- 3. Store / transport cartons in the correct direction, which is indicated on a carton with a symbol. Otherwise bent leads may occur due to excessive stress applied when dropping of a carton.
- 4. Use Products within the specified time after opening a humidity barrier bag. Baking is required before using Products of which storage time is exceeding the recommended storage time period.

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# RD3P08BBD - Web Page

Part Number	RD3P08BBD
Package	TO-252
Unit Quantity	2500
Minimum Package Quantity	2500
Packing Type	Taping
Constitution Materials List	inquiry
RoHS	Yes